

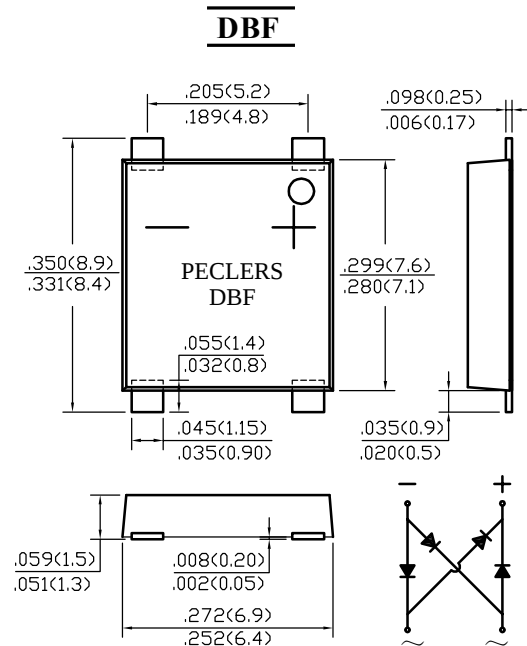
REVERSE VOLTAGE: 1200 VOLTS
FORWARD CURRENT: 4.0 AMPERE

FEATURE

- Glass passivated junction.
- Ideal for printed circuit board.
- Reliable low cost construction utilizing molded plastic technique.
- High surge current capability.
- High temperature soldering guaranteed: 260°C/10 seconds at terminals.

MECHANICAL DATA

- Case: Molded plastic, DBF
- Epoxy: UL 94V-O rate flame retardant
- Terminals: Leads solderable per MIL-STD-202, method 208 guaranteed
- Mounting position: Any
- Weight: 0.204g (approximately)



Dimensions in inches and (millimeters)

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25°C ambient temperature unless otherwise specified.

Single phase, half wave, 60Hz, resistive or inductive load.

For capacitive load, derate current by 20%

Type Number	SYM BOL	DBF410H	units
Maximum Recurrent Peak Reverse Voltage	V_{RRM}	1200	V
Maximum RMS Voltage	V_{RMS}	840	V
Maximum DC blocking Voltage	V_{DC}	1200	V
Maximum Average Forward rectified Current @ $T_A=40^\circ\text{C}$	$I_{F(AV)}$	4.0	A
Peak Forward Surge Current 8.3ms single half sine-wave superimposed on rate load (JEDEC method)	I_{FSM}	150	A
Maximum Instantaneous Forward Voltage @ $I_F=2.0\text{A DC}$ @ $I_F=4.0\text{A DC}$	V_F	1.0 1.1	V
Maximum DC Reverse Current @ $T_J=25^\circ\text{C}$ at rated DC blocking voltage @ $T_J=125^\circ\text{C}$	I_R	5.0 500.0	μA
Typical Junction Capacitance Per Leg (Note1)	C_J	50	pF
Typical Thermal Resistance (Note2)	R_{JA}	60	$^\circ\text{C/W}$
	R_{JC}	10	
Storage Temperature	T_{STG}	-55 to +150	$^\circ\text{C}$
Operating Junction Temperature	T_J	-55 to +150	$^\circ\text{C}$

Note:

1. Measured at 1.0 MHz and applied reverse voltage of 4.0Vdc
2. Mounted on glass epoxy PC board with 4×1.5"×1.5" (3.81×3.81 cm) copper pad.

RATINGS AND CHARACTERISTIC CURVES

FIG.1-TYPICAL FORWARD CURRENT DERATING CURVE

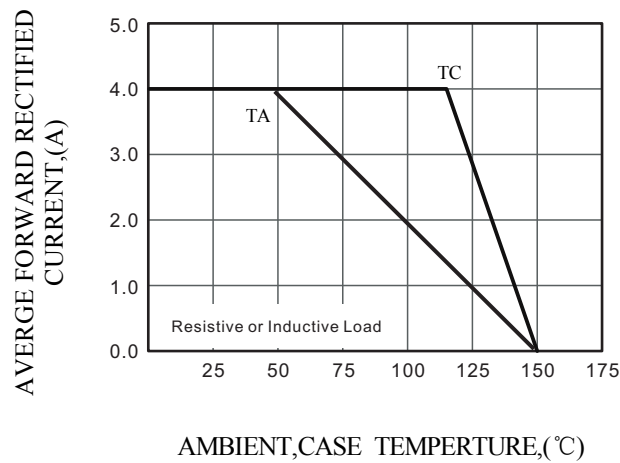


FIG.3-MAXIMUN NON-REPETITIVE FORWARD SURGE CURRENT

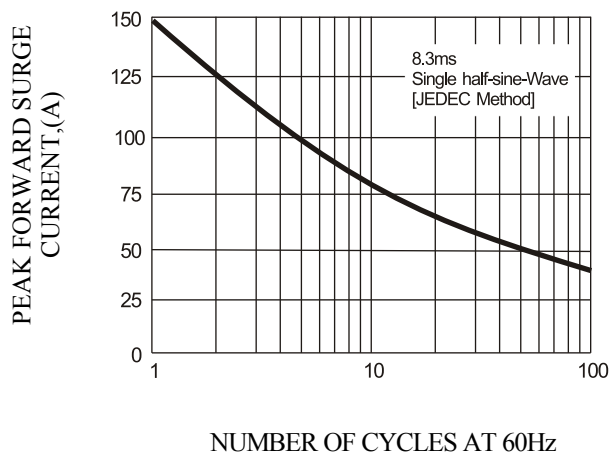


FIG.5-TYPIAL JUNCTION CAPAOTANCE

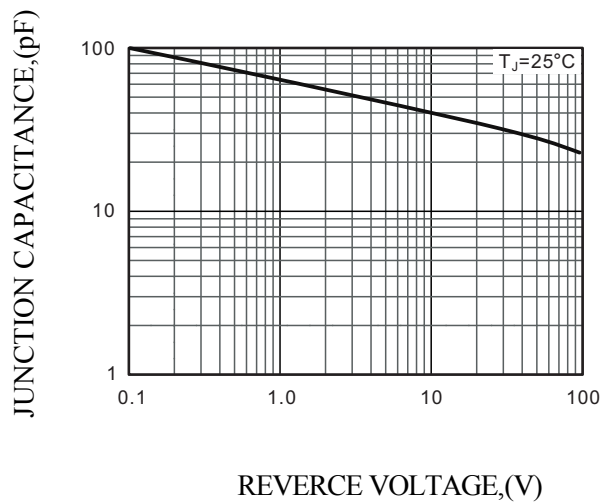


FIG.2-TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS

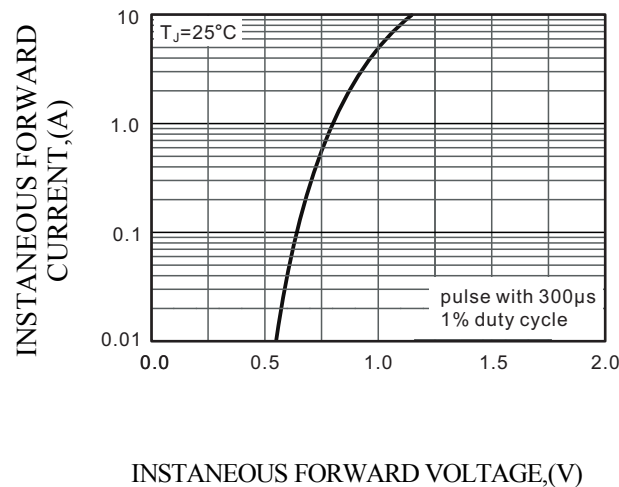


FIG.4-TYPICAL REVERSE CHARACTERISTICS

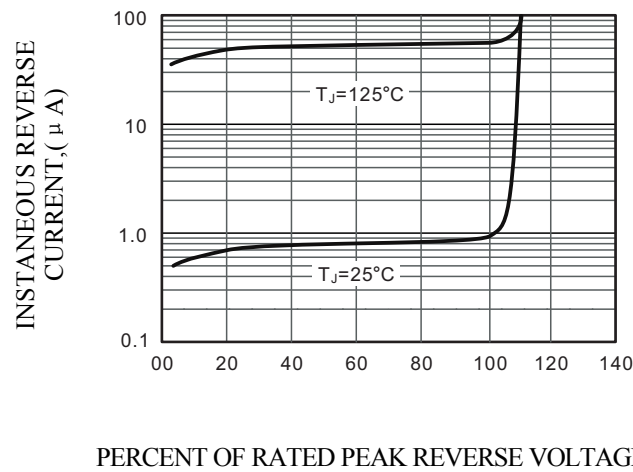


FIG.6 MOUNTING PAD LAYOUT

